

A. Interconnect & Package 분과

2020년 2월 13일(목), 10:45-12:45 / Room I (하트 II, 6층)

■ [T12-A] Interconnect & Packaging

좌장: 김성동 교수 (서울과학기술대학교)

T12-A-1 10:45-11:15	<p>[초청]</p> <p>Development of a Planar-type Thermoelectric Cooling Device for Mobile Electronic Products: Deposition, Device Fabrication Process, and Thermal Performance</p> <p>Hoo-Jeong Lee¹, Hae-sun Shin², Chul Kim³, and Young-chang Joo³</p> <p>¹<i>Department of Advanced Materials Science and Engineering, Sungkyunkwan University,</i> ²<i>Korea Research Institute of Chemical Technology,</i> ³<i>Department of Materials Science and Engineering, Seoul National University</i></p>
T12-A-2 11:15-11:45	<p>[초청]</p> <p>Thermo-Mechanical Reliability and Properties Evaluation for Advanced Electronic Packages</p> <p>Tae-Ik Lee</p> <p><i>KITECH</i></p>
T12-A-3 11:45-12:00	<p>Laser-Assisted Bonding (LAB) – Versatile Enabling Technology for the 4th Industrial Revolutions</p> <p>Kwang-Seong Choi, Jiho Joo, Ki-seok Jang, Gwang-Mun Choi, Ho-Gyeong Yun, Seok Hwan Moon, and Yong-Sung Eom</p> <p><i>ICT Creative Laboratory, ETRI</i></p>
T12-A-4 12:00-12:15	<p>Spin-Related Resistances in Ferromagnetic/Nikelate Bilayers</p> <p>Se Yeob Jeong¹, Jongmin Lee², Nyun Jong Lee¹, Sanghan Lee², Tae Heon Kim¹, and Sanghoon Kim¹</p> <p>¹<i>Department of Physics, University of Ulsan,</i> ²<i>School of Materials Science & Engineering, GIST</i></p>
T12-A-5 12:15-12:30	<p>Density Functional Theory Study on the Atomic Layer Deposition of Tungsten by Using Tungsten Chloride</p> <p>Yewon Kim¹, Romel Hidayat¹, Soo-Hyun Kim², and Won-Jun Lee¹</p> <p>¹<i>Department of Nanotechnology and Advanced Materials Engineering, Sejong University,</i> ²<i>School of Materials Science and Engineering, Yeungnam University</i></p>
T12-A-6 12:30-12:45	<p>Novel PCT Laminated Busbar for Enhanced Current Transfer Characteristics</p> <p>Kyongdo Kim¹, Soonkon Kim², and Byoungdeog Choi²</p> <p>¹<i>Jinyoung Global co.,LTD,</i> ²<i>Department of Electrical and Computer Engineering, Sungkyunkwan University</i></p>